Welcome to O-leading

Ceramic Printed circuit board supplier

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service – S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

PLEASE CLICK HERE FOR MORE INFORMATION: High Quality Ceramic PCB supplier

Product Description

PCB P/N	Q56253-Н
Layer count	2L
Material	FR-4
Board thk	1.60mm
copper thk	1/1oz
Smallest hole size	1.6mm
No.of holes (pcs)	668
Impedance control. Y / N (Tol %)	N







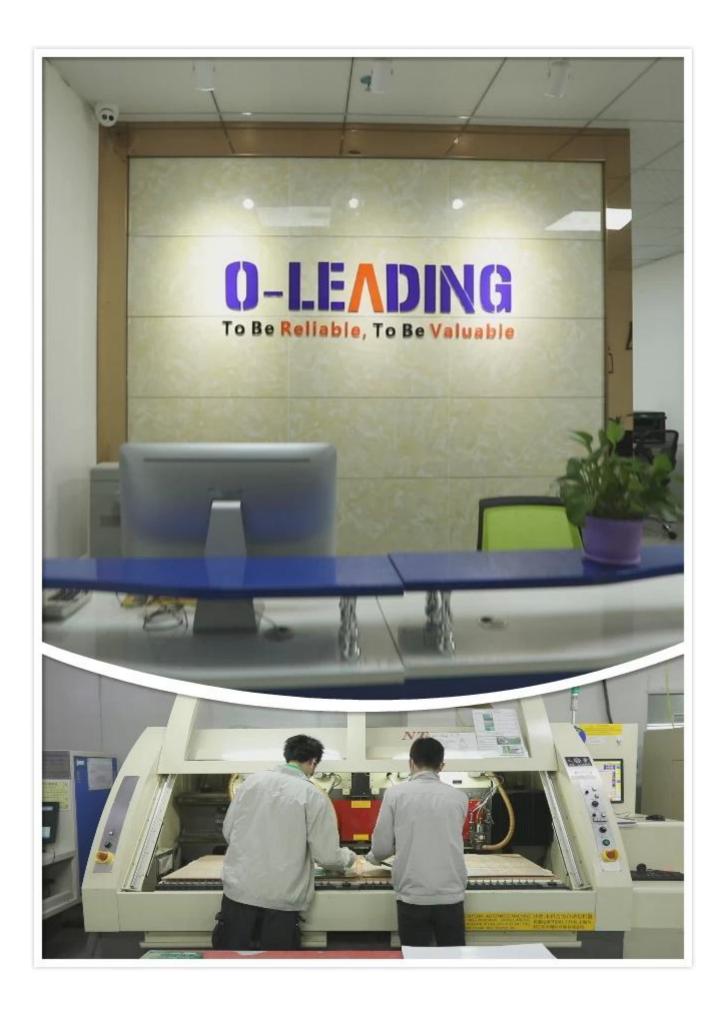






DCB Ceramic PCB suppliers china

Our Team





Certifications





QUALITY MANAGEMENT SYSTEM CERTIFICATE

We hereby certify that O-LEADING SUPPLY CHAIN(HK) CO., LIMITED

Credit No: 61691591-000-07-17-2 Registration Act ROOM 6030.6F HANG PONT COMMERCIAL BULDING,31 TONKIN ST,CHEUNG SHA WAN,KI,HK Business Act 1313 Floor 13 Forture Building,Danstru Town,Huyang District, Huchou, Guangdong,Chris

Has implemented and maintains a Quality Management System

Which fulfils the requirements of the following standards GB/T19001-2016 ldt ISO9001:2015

Scope of certification

Sales of printed circuit boards

mark

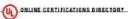
Initial Issuance period: February 27, 2018 This certificate is valid during: February 27, 2018 — February 26, 2021 This certificate is invalid without CICC qualified label in the following period

First	0.000	Second	
supervision	Qualified	supervision	Q:
and audit	man	and audit	

CICC TAB CNAS

2017/26

ZPWVZE40054 - Winny, Printed - Component



ZPMV2.E490354 Wiring, Printed - Component

For enhanced search functionality, please visit 0.1×10^{-6} Family of Databases. Citix on a product designation for complete information.

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

O-LEADING SUPPLY CHAIN CO LIMITED

E490354

Fortune Building, Nanhang West Road Room 131,3 Huithou, Guangdons 516211 CHINA

Main Edge Thick D5/ Diam Limit Temp Plans UL791		Cond	Width	1		Max	. 9		Max			
Type men(in) men(in) men(ini) men(ini) Deb men(in) C Sec C C Deb Deb HullEtyper (masc lambase) printed wiring boards. O-LEADING-402 O-LEADING-403 0.3 (0.0312) 0.4 (0.34) De 1.2 (0.05) Deb Deb 1.2 (0.05) Deb 1.2 (0.05) Deb 1.2 (0.05) Deb Deb	Т		Min	Cond	SS/	Aren	Sol	der	Oper		Nests	4
Hullistyer (mass instructe) printed wiring boards. O-16/0014 0.3 (0.012) 34 (1.34) D6 12.7 (0.5) 260 10 130 V-0 - O-16/0016-402 O-16/0016-402 0.3 (0.012) 37 (0.67) D5 9.7 (0.4) 260 10 130 V-0 Al Hullistyer printed wiring boards. O-16/0016-408 0.125 (0.005) 0.125 (0.005) 12 (0.47) D5 59.8 (2.0) 280 20 130 V-0 Al Hullistyer printed wiring boards. O-16/0016-408 0.125 (0.005) 0.125 (0.005) 12 (0.47) D5 59.8 (2.0) 280 20 130 V-0 Al Single bayer printed wiring boards. O-16/0016-408 0.125 (0.005) 0.12		Min	Edge	This	D5/	Diam	Lin	ette	Tump	Flame	UL796	,
O-LEADING-HO1 0.1 (0.004) 0.3 (0.012) 34 (1.34) 06 12.7 (0.5) 260 10 130 V-0 - O-LEADING-HO7 0.08 (0.003) 0.2 (0.008) 17 (0.67) 75 9.7 (0.4) 260 10 130 V-0 All Multitayer primter wir high beards. O-LEADING-HO3 0.125 (0.005) 0.125 (0.005) 12 (0.07) 05 59.8 (2.0) 280 20 130 V-0 All Single Byer printer wiring boards. O-LEADING-HO3 0.18 (0.015) 1.14 (0.045) 34 (1.34) 35 19.1 (0.0) 760 10 105 V-0 All O-LEADING-HO3 0.38 (0.015) 1.14 (0.045) 34 (1.34) 35 19.1 (0.0) 260 10 130 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 35 25.8 (1.0) 260 10 120 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.8 (1.0) 260 10 120 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.8 (1.0) 260 10 130 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.8 (1.0) 260 10 130 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.8 (1.0) 260 10 100 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.8 (1.0) 260 10 100 V-0 All O-LEADING-HO3 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.8 (1.0) 260 10 100 V-0 All O-LEADING-HO3	ж	mm(in)	mm(in)	mic(mil)	090	me(in)	c	sec	c	Class	DSR	ī
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0-4EADING-407 0-06 (0.003) 0-2 (0.006) 17 (0.67) 05 9-2 (0.4) 260 10 130 V-0 MI MURITAGE PRIMARY PRIMARY BEARDS. 0-1EADING-408 0-125 (0.005) 0.125 (0.005) 12 (0.07) 05 95.8 (2.0) 280 20 130 V-0 MI Single byer primary wiring beards. 0-16 DING-408 0-17 (0.015) 1.14 (0.045) 36 (1.34) 55 19.1 (0.0) 260 10 105 V-0 MI 0-18 DING-003 0-18 (0.015) 1.14 (0.045) 36 (1.34) 55 19.1 (0.8) 260 10 130 V-0 MI 0-18 DING-003 0-18 DING-004 0-18 DING-003	LEAD	DING-401										Т
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Hullistager printed wiring boards.	LEAL	DING-407										
O-LEADING-408 0.125 (0.005) 0.125 (0.005) 12 (0.47) D6		0.08 (0.003)	0.2 (0.008)	17 (0-67)	DS	9.7 (0.4)	260	10	130	V-0	All	ŀ
C.125 (0.005) 0.125 (0.005) 12 (0.07) D6 50.8 (2.0) 280 20 130 V-0 M	Ella	yer printed w	iring boards.									•
Initial Init	LEAD	DING-408	6							00	-0. 0	. 3
O-LEADING-002 0.78 (6.015) 1.14 (0.045) 34 (1.34) 55 19.1 (0.0) 260 10 105 V-0 M O-LEADING-003 0.38 (6.015) 1.14 (0.045) 34 (1.34) 55 19.1 (0.0) 260 10 130 V-0 ▲ O-LEADING-035 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.4 (1.0) 260 10 120 V-0 M O-LEADING-205 0.3 (0.004) 0.3 (0.012) 34 (1.34) 55 25.4 (1.0) 260 10 120 V-0 M O-LEADING-205	1	0.125 (0.005)	0.125 (0.005)		DS	50.8 (2.0)	280	20	130	940	All	ŀ
0.78 (0.015) 1.14 (0.045) 30 (1.34) 55 19.1 (0.0) 260 10 105 9-0 Al	gle	layer printed	wiring boards.									
0-LEADING-003 C.38 (6.015)	LEAD	DIN6-002	0		rs. 6	33 11					3 .	Ī
0.38 (0.015) 1.14 (0.045) 34 (1.34) 58 19.1 (0.8) 260 10 130 № O-LEADING-033 0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.4 (1.0) 260 10 120 № O-LEADING-205 0.1 [0.004] 0.3 (0.012) 54 (1.34) 05 89.8 (2.7) 260 10 130 № All	T	0.78 (0.015)	1.14 (0.045)	34 (1,34)	55	(9.1 (0.0)	260	10	105	V-0	M	ŀ
0-1EADING-033 0.15 (6.006) 0.3 (0.012) 34 (1.34) 55 25.4 (1.0) 260 10 120 9-0 48 0-1EADING-205 0.1 [0.004] 0.5 (0.012) 54 (1.34) 05 89.6 (2.7) 260 10 130 9-0 48	LEAD	DING-003				3 8						
0.15 (0.006) 0.3 (0.012) 34 (1.34) 55 25.4 (1.0) 260 10 120 9-0 44 0-1CADING-205 0.3 (0.004) 0.5 (0.012) 54 (1.34) 05 89.6 (2.7) 260 10 130 9-0 44	T	0.38 (0.015)	1.14 (0.045)	34 (1,34)	55	19.1 (0.8)	260	10	130	940	A	ŀ
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0.1 [0.004]		0.15 (0.006)	0.3 (0.012)	34 (1,34)	55	25.4 (1.0)	260	10	120	9-0	44	ŀ
	LEAD	DING-205		3								
2.00.00.20.00	1	0.1 [0.004]	0.5 (0.012)	34 (1.34)	DS .	69.6 (2.7)	250	10	130	V+0	All .	-
O-LEADING-206	LEAL	DING-206		510	63 V							
0.15 (0.006) 0.33 (0.013) 17 (0.67) 05 69-6 (2-7) 260 10 130 9-0 44	1	0.15 (0.006)	0.33 (0.013)	17 (0-67)	DS .	69-6 (2-7)	260	10	130	9-0	All .	

* - CTI marking is optional and may be marked on the printed wiring board.

Nording: Company name or file number and type designation. Nay be followed by a suffix to desoite factory identification or burning text desoitedation. Last ligitated on 2017-91-27

Questions? Print this gage Terms of Use rapidatase Journa (BAYVInglandSEKT/ERVINELLogoga) milkare ZEMVZ, Edition Landaudi Villing (Printe) +Corporation (- 12 SGS

Test Report

No. CANEC1805164701

Date: 03 Apr 2018 Page 2 of 6

Test Results :

Test Part Description :

scimen No. SGS Sample ID Description SN1 CAN18-051647.001 Green "PCB"

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit (3) ND = Not Detected (< MDL) (4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method: With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7:22017, IEC 62321-6:2015 and IEC62321-6:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test item(s)	Limit	Unit	MOL	001
Cadmium (Cd)	100	mg/kg	2	NO
Lead (Pb)	1.000	mg/kg	2	9
Mercury (Hg)	1.000	mg/kg	2	NO
Hexavalent Chromium (CrVI)	1.000	mg/kg	8	NO
Sum of PBBs	1,000	mg/kg	12	NO
Manobromobiphenyl		mg/kg	5	NO
Dibromobiphenyl		mg/kg	5	NO
Tribromobiphenyl	4	mg/kg	5	NO
Tetrabromobiphenyl		mg/kg	5	NO
Pentatromotiphenyl		mg/kg	5	NO
Hexabromobiphenyl		mg/kg	5	NO
Heptabromobiphenyl		mg/kg	- 5	NO
Octabromobiphenyl		mg/kg	5	NO
Nonabromobiphenyl		mg/kg	5	NO
Decabromobiphenyl	7.5	mg/kg		ND
Sum of PBDEs	1.000	mg/kg	12	NO
Manabromodipheryl ether		mg/kg	5	NO
Dibromodiphenyl ether	-	mg/kg	5	NO
Tribromodiphenyl ether	4	mg/kg	5	NO
Tetrabromodiphenyl ether		mg/kg	5	NO
Pentahromodioheral ether		mafea		MO



Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days



FAQ

- 1. How do O-Leading ensure quality?
- Our high quality standard is achieved with the following.
- 1. The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4. Dedicated quality assurance team with failure case analysis process
- 5. Continuous staff training and education
- 2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.

- 3. What kinds of boards can O-Leading process? Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.
- 4. What data are needed for PCB production? It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.
- 5. What's the typical process flow for multi-layer PCB? Material cutting \rightarrow Inner dry film \rightarrow inner etching \rightarrow Inner AOI \rightarrow Multi-bond \rightarrow Layer stack up Pressing \rightarrow Drilling \rightarrow PTH \rightarrow Panel Plating \rightarrow Outer Dry Film \rightarrow Pattern Plating \rightarrow Outer etching \rightarrow Outer AOI \rightarrow Solder Mask \rightarrow Component Mark \rightarrow Surface finish \rightarrow Routing \rightarrow E/T \rightarrow Visual Inspection.